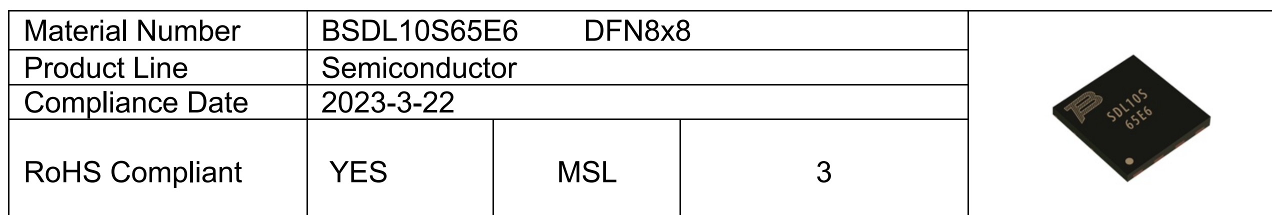
MATERIAL DECLARATION SHEET



Material Number	BSDL10S65E6 DFN8x8			
Product Line	Semiconductor			
Compliance Date	2023-3-22			
RoHS Compliant	YES	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	1.74	Silicon Carbide (SiC)	409-21-2	100	1.02	1.02
2	Die Attach	Silver	0.02	Hardener	288-32-4	5	0.01	0.24
			0.02	Phenolic resin	9003-35-4	5	0.01	
			0.02	Epoxy resin system	24969-06-0	5	0.01	
			0.36	Silver (Ag)	7440-22-4	85	0.21	
3	Lead Frame	Copper alloy	0.02	Phosphorous (P)	7723-14-0	0.03	0.01	38.06
			0.1	Zinc (Zn)	7440-66-6	0.15	0.06	
			1.49	Iron (Fe)	7439-89-6	2.29	0.87	
			63.19	Copper (Cu)	7440-50-8	96.97	36.91	
			0.36	Silver (Ag)	7440-22-4	0.56	0.21	
4	Mold Compound	Resin	3.49	Epoxy Phenol Novolac resin (generic)	28064-14-4	3.5	2.04	58.24
			7.98	Silica -amorphous-	7631-86-9	8	4.66	
			79.76	Silica fused	60676-86-0	80	46.59	
			0.5	Carbon black	1333-86-4	0.5	0.29	
			7.98	Epoxy resin system	85964-11-6	8	4.66	
5	Post-plating	Pure metal	3.1	Tin (Sn)	7440-31-5	100	1.81	1.81
6	Wire	Metal	1.08	Copper (Cu)	7440-50-8	99.99	0.63	0.63
		Total weight	171.21 mg					

This Document was updated on: 2023/3/22

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which is exempt from the requirements

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society